

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHIH-LIANG CHEN</td> <td>12/18/2013</td> </tr> <tr> <td>JIANN-TYNG TZENG</td> <td>12/18/2013</td> </tr> <tr> <td>SHU-HUI SUNG</td> <td>12/18/2013</td> </tr> <tr> <td>CHARLES CHEW-YUEN YOUNG</td> <td>12/31/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHIH-LIANG CHEN	12/18/2013	JIANN-TYNG TZENG	12/18/2013	SHU-HUI SUNG	12/18/2013	CHARLES CHEW-YUEN YOUNG	12/31/2013
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CORRESPONDENCE DATA											
<p>Fax Number:</p> <p>Phone: 2166540090</p> <p>Email: docketing@cooperlegalgroup.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: COOPER LEGAL GROUP LLC</p> <p>Address Line 1: 6505 ROCKSIDE ROAD SUITE 330</p> <p>Address Line 4: INDEPENDENCE, OHIO 44131</p>											
ATTORNEY DOCKET NUMBER:	TSMC2013-1584										
NAME OF SUBMITTER:	DANIEL A. TATE										
Signature:	/Daniel A. Tate/										

Date:

02/02/2014

Total Attachments: 2

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ASSIGNMENT

For good and valuable consideration received of the hereinafter named assignee, receipt of which is hereby acknowledged, the undersigned

Chih-Liang Chen
Hsinchu City, TW

Jiann-Tyng Tzeng
Hsin Chu, TW

Shu-Hui, Sung
Baoshan Township, TW

Charles Chew-Yuen Young
Cupertino, CA, USA

NOW, THEREFORE, for and in consideration of our employment and the salary or wages paid to us by Taiwan Semiconductor Manufacturing Company Limited, I/we, Chih-Liang Chen, Jiann-Tyng Tzeng, Shu-Hui Chang and Charles Chew-Yuen Young, by these presents do sell, assign, and transfer unto said Taiwan Semiconductor Manufacturing Company Limited, a corporation organized and existing under the laws of the Republic of China, having its principal place of business at No. 8, Li-Hsin Road 6, Hsin-Chu Science Park, Hsin-Chu, Taiwan 300-77, R.O.C., is desirous of acquiring an interest therein, its successors and assigns, the entire right, title and interest, so far as concerns the United States and the Territories and Possessions thereof and all foreign countries, in and to the inventions entitled

THERMAL ANALYSIS FOR TIERED SEMICONDUCTOR STRUCTURE

for which application for United States Letters Patent has been filed on _____ under Serial No. _____, or was executed by the undersigned on the date below and is being filed concurrently herewith, said application for United States Letters Patent, any and all other applications for Letters Patent on said inventions in countries foreign to the United States, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or upon said applications, and any and all Letters Patent and reissues and extensions of Letters Patent granted for said inventions or upon said applications, and every priority right that is or may be predicated upon or arise from said inventions, said applications and said Letters Patent; said assignee being hereby authorized to file patent applications in any or all countries on any or all said inventions in the name of the undersigned or in the name of said assignee or otherwise as said assignee may deem advisable, under the International Convention or otherwise; the Commissioner of Patents and Trademarks of the United States of America and the empowered officials of all other governments being hereby authorized to issue or transfer all said Letters Patent to said assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had by the undersigned, but also that such assigned right is not encumbered by any grant, license, or other right heretofore given, and that the undersigned will do all acts reasonably serving to assure that said inventions, patent applications and Letters Patent shall be held and enjoyed by said assignee as fully and entirely as the same could have been held and enjoyed by the undersigned if this assignment had not been made, and particularly to execute and deliver to said assignee all lawful documents including petitions, specifications, oaths, assignments, invention disclaimers, and lawful affidavits in form and substance which may be requested by said assignee, to furnish said assignee with all facts relating to said inventions or the history thereof and any and all documents, photographs, models,

samples or other physical exhibits which may be useful for establishing the facts of conception, disclosure and reduction to practice of said inventions, and to testify in any proceedings relating to said inventions, patent applications and Letters Patent.

<u>Chih-Liang Chen</u>	<u>2013/12/18</u>
Inventor's Signature	Date
<u>Chih-Liang Chen</u>	
Printed Name in English	

<u>Giann-Tyng Tzeng</u>	<u>2013/12/18</u>
Inventor's Signature	Date
<u>Giann-Tyng Tzeng</u>	
Printed Name in English	

<u>[Signature]</u>	<u>2013/12/18</u>
Inventor's Signature	Date
<u>Shu-Hui Chang SUNG</u>	
Printed Name in English	

<u>[Signature]</u>	<u>2013/12/18</u>
Inventor's Signature	Date
<u>Charles Chew-Yuen Young</u>	
Printed Name in English	